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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
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**In re Application of:**

Akram et al.

**Serial No.:** 09/241,177

**Filed:** February 1, 1999

**For:** HIGH DENSITY MODULARITY FOR  
IC'S

**Examiner:** C. Novacek


**Group Art Unit:** 2822

**Attorney Docket No.:** 3638US (98-0093)

CERTIFICATE OF MAILING

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Jayna M. Lofgran  
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AMENDMENT

Box NON-FEE AMENDMENT  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

This amendment is in response to the Office Action of September 18, 2001 whose initial period of response is set to expire on December 18, 2001.